



PRODUCT DATA SHEET



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Datasheet



Resources

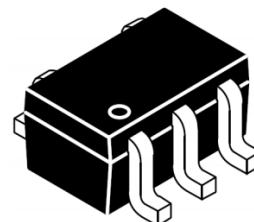


Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

Features

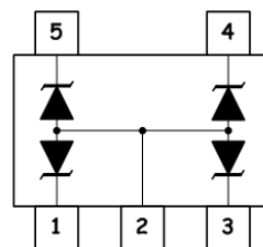
- Ultra low leakage: nA level
- Operating voltage: 5V
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 30\text{kV}$
 - Contact discharge: $\pm 30\text{kV}$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 3A (8/20 μs)
- RoHS Compliant



SOT-353

Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet



Mechanical Characteristics

- Package: SOT-353
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel: 3,000 pcs
- Reel Size: 7 inch

Absolute Maximum Ratings (T_{amb}=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	P _{pp}	100	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	± 30	Kv
ESD per IEC 61000-4-2 (Contact)		± 30	
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{STJ}	-55 to +150	°C

Electrical Characteristics (TA=25°C unless otherwise specified)

Part Number	V _{RWM} (V)	V _{BR} (V)	I _T (mA)	V _C @1A	V _C		I _R μA (Max)	C (Pf) (Typ.)
					(Max)	(@A)		
ESDA6V1W5	5	6	1	9.8	18.5	3	2	30

Characteristic Curves

Fig1. 8/20 μs Pulse Waveform

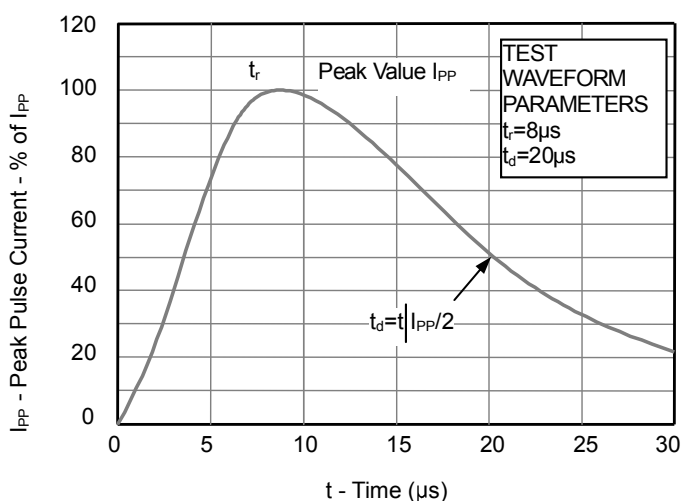


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

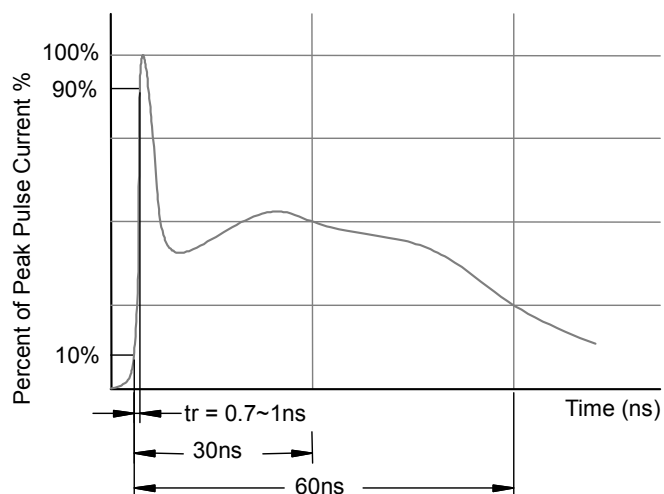
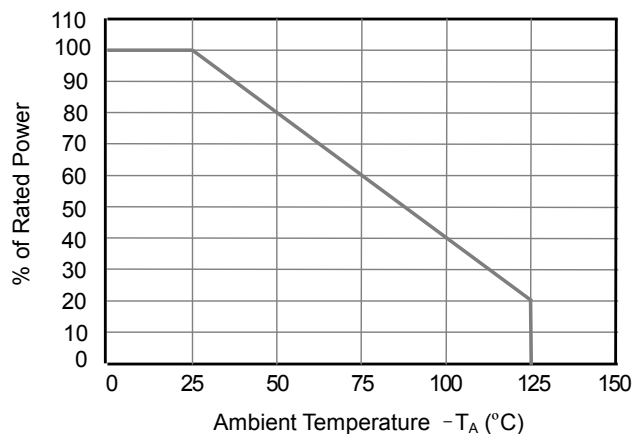
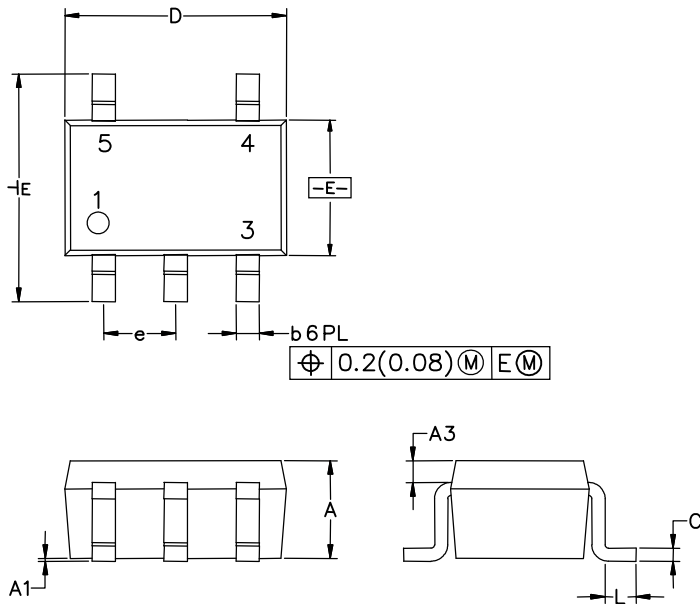


Fig3. Power Derating Curve

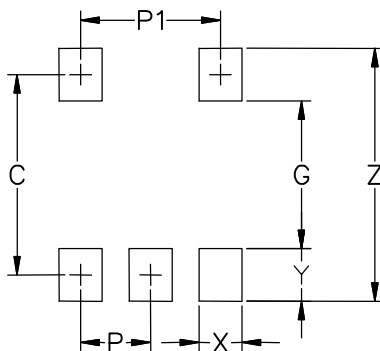


SOT-353 Package Outline & Dimensions



Symbol	Inches			Millimeters		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.031	0.037	0.043	0.80	0.95	1.10
A1	0.000	0.002	0.004	0.00	0.05	0.10
A3	0.08 REF			0.2 REF		
b	0.004	0.008	0.012	0.10	0.21	0.30
C	0.004	0.005	0.010	0.10	0.14	0.25
D	0.070	0.078	0.086	1.80	2.00	2.20
E	0.045	0.049	0.053	1.15	1.25	1.35
e	0.026 BSC			0.65 BSC		
L	0.004	0.008	0.012	0.10	0.20	0.30
H _E	0.078	0.082	0.086	2.00	2.10	2.20

Soldering Footprint



Symbol	Inches	Millimeters
C	0.0748	1.9
G	0.055	1.40
P	0.025	0.65
P1	0.051	1.30
X	0.0157	0.40
Y	0.019	0.50
Z	0.0945	2.4

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